

N-Channel Enhancement Mode MOSFET

1. Product Information

Features

- Advanced trench technology
- Excellent $R_{DS(ON)}$
- Low gate charge

Applications

- Battery protection
- Load switch
- Uninterruptible power supply

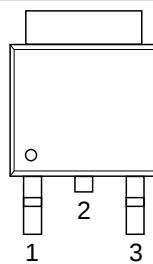
Quick reference

- $V_{DS} = 60V$
- $I_D = 50A$
- $R_{DS(ON)} \leq 16m\Omega @ V_{GS} = 10V$ (Type:11m Ω)

Pin Description

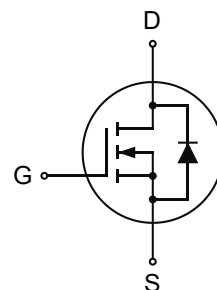
Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

Simplified Outline



Top View
TO-252

Symbol



Package Marking and Ordering Information

Product Name	Package	Marking	Reel size	Tape width	Quantity (pcs)
KJ50N06K	TO-252	50N06 XXXXXX	13"	24 mm	2500

2. Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ ¹	50	A
$I_D @ T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ ¹	32	A
I_{DM}	Pulsed Drain Current ²	150	A
E_{AS}	Single Pulse Avalanche Energy ³	72	mJ
I_{AS}	Avalanche Current	38	A
$P_D @ T_C=25^\circ C$	Total Power Dissipation ⁴	45	W
T_J, T_{stg}	Operating Junction and Storage Temperature	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.8	$^\circ C/W$

3. Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	65	-	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.057	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A	-	11	16	mΩ
		V _{GS} =4.5V, I _D =10A	-	16	20	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250μA	1.2	1.8	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		-	-5.68	-	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =48V, V _{GS} =0V, T _J =25°C	-	-	1	μA
			-	-	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =15A	-	45	-	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	-	1.7	-	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =48V V _{GS} =4.5V I _D =30A	-	19.3	-	nC
Q _{gs}	Gate-Source Charge		-	7.1	-	
Q _{gd}	Gate-Drain Charge		-	7.6	-	
t _{d(on)}	Turn-On Delay Time	V _{DD} =30V, V _{GS} =10V R _G =3.3Ω, I _D =15A	-	7.2	-	ns
t _r	Rise Time		-	50	-	
t _{d(off)}	Turn-Off Delay Time		-	36.4	-	
t _f	Fall Time		-	7.6	-	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	2423	-	pF
C _{oss}	Output Capacitance		-	145	-	
C _{rss}	Reverse Transfer Capacitance		-	97	-	
I _S	Continuous Source Current ^{1,5}	V _{GS} =V _{DS} =0V, Force Current	-	-	35	A
I _{SM}	Pulsed Source Current ^{2,5}		-	-	80	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	-	-	1	V
t _{rr}	Reverse Recovery Time	I _F =15A, dI/dt=100A/μs, T _J =25°C	-	16.3	-	ns
Q _{rr}	Reverse Recovery Charge		-	11	-	nC

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%.
3. The E_{AS} data shows Max. rating. The test condition is V_{DD}=30V, V_{GS}=10V, L=0.5mH, I_{AS}=38A.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

4. Typical Characteristics

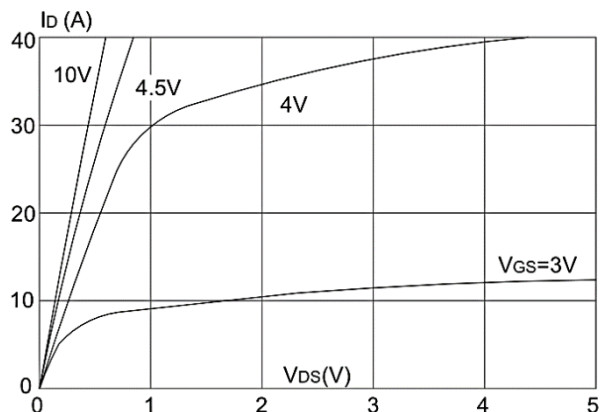


Figure1: Output Characteristics

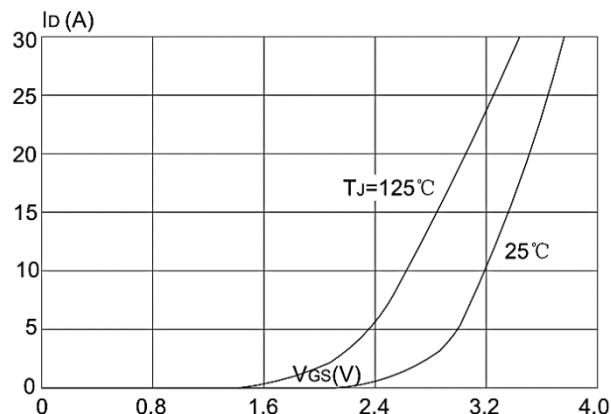


Figure 2: Typical Transfer Characteristics

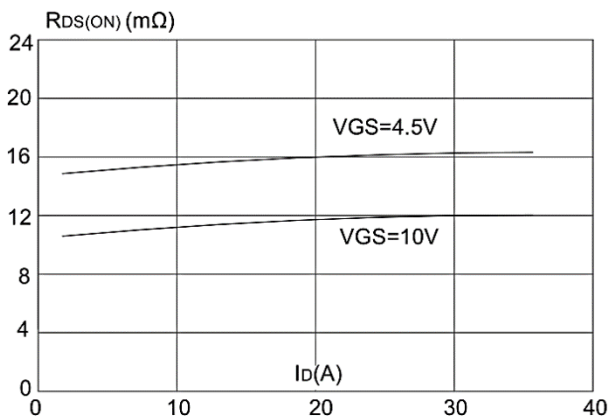


Figure 3: On-resistance vs. Drain Current

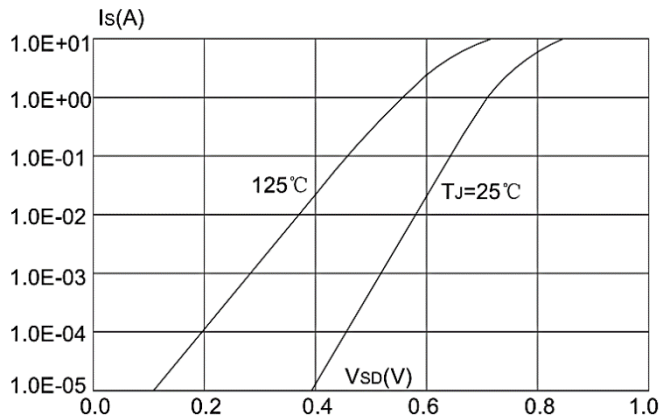


Figure 4: Body Diode Characteristics

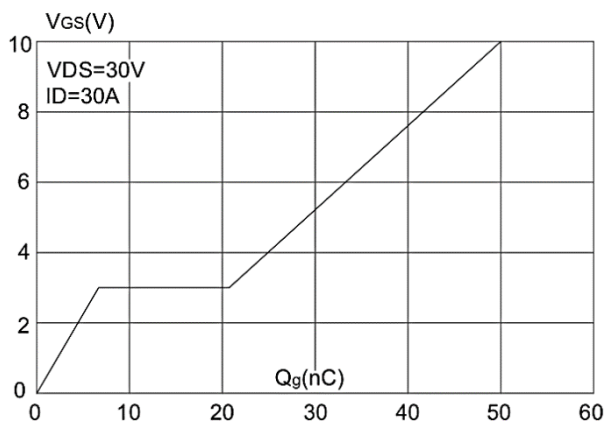


Figure 5: Gate Charge Characteristics

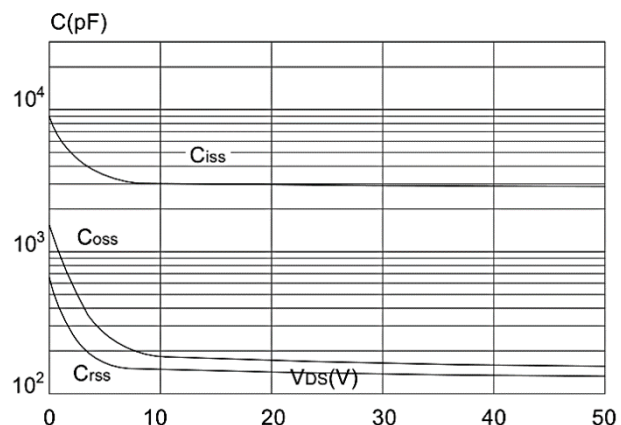


Figure 6: Capacitance Characteristics

4. Typical Characteristics (cont.)

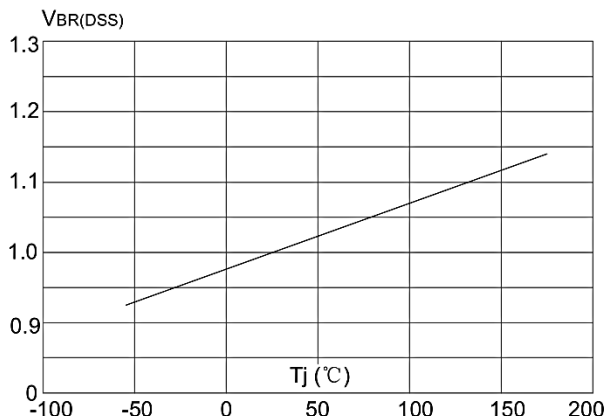


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

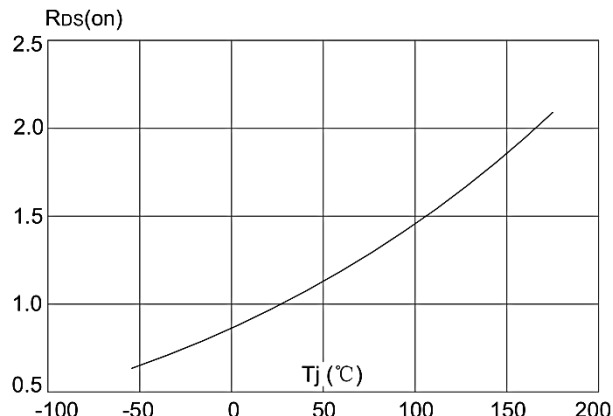


Figure 8: Normalized on Resistance vs. Junction Temperature

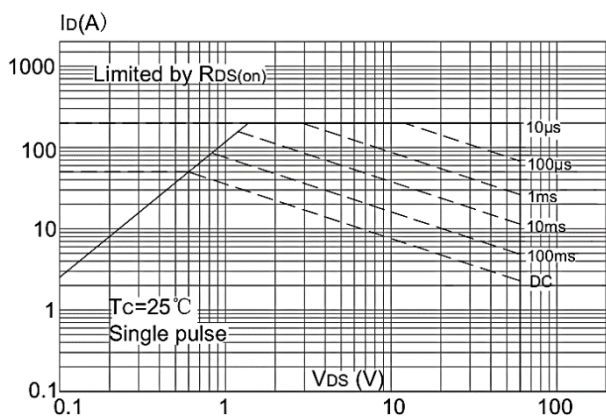


Figure 9: Maximum Safe Operating Area

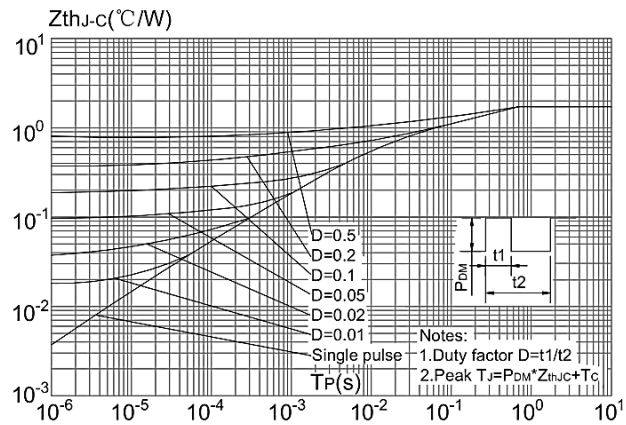


Figure.10: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien

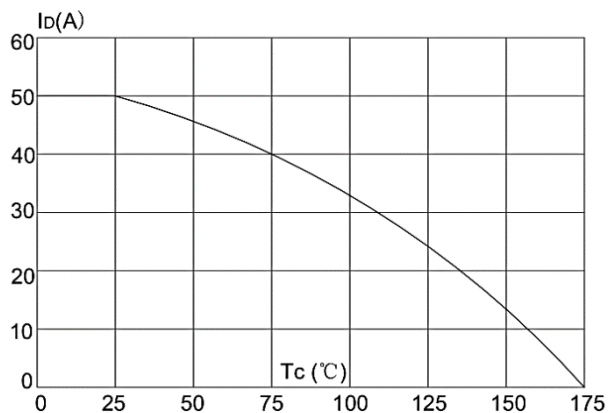
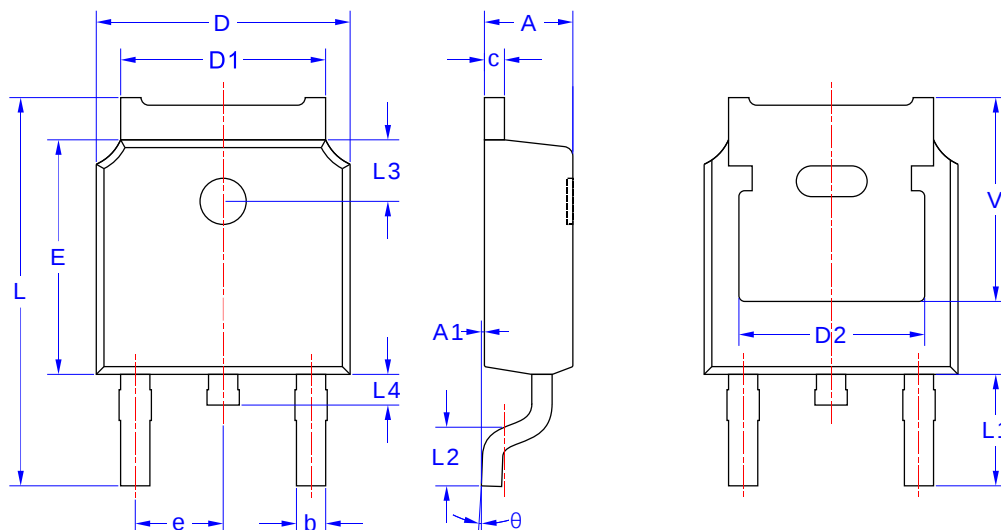


Figure 11: Maximum Continuous Drain Current vs. Ambient Temperature

5. Package Mechanical Data

TO-252 Package



Symbol	Dimensions in Millimeters	
	MIN	MAX
A	2.200	2.400
A1	0	0.127
b	0.660	0.860
c	0.460	0.580
D	6.500	6.700
D1	5.100	5.460
D2	4.830 REF.	
E	6.000	6.200
e	2.186	2.386
L	9.800	10.400
L1	2.900 REF.	
L2	1.400	1.700
L3	1.800 REF.	
L4	0.600	1.000
θ	0°	8°
V	5.600 REF.	